General Purpose Transistors

PNP Silicon

Features

• These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-60	Vdc
Collector – Base Voltage	V _{CBO}	-60	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	۱ _C	-600	mAdc
Collector Current – Peak (Note 3)	I _{CM}	-1200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) @T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

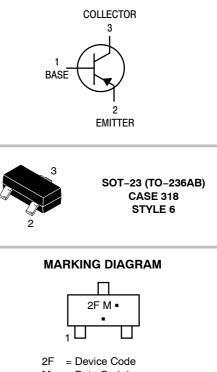
2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

3. Reference SOA curve.



ON Semiconductor®

http://onsemi.com



M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location) *Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT2907ALT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBT2907ALT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

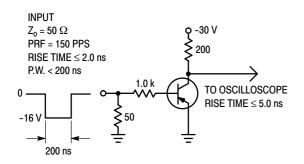
+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Charac	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
$ Collector-Emitter Breakdown Voltage (Not (I_C = -1.0 mAdc, I_B = 0)) \\ (I_C = -10 mAdc, I_B = 0) $	V _{(BR)CEO}	-60 -60		Vdc	
Collector – Base Breakdown Voltage (I_C =	= −10 μAdc, I _E = 0)	V _{(BR)CBO}	-60	-	Vdc
Emitter – Base Breakdown Voltage (I_E = -	-10 μAdc, I _C = 0)	V _{(BR)EBO}	-5.0	-	Vdc
Collector Cutoff Current (V_{CE} = -30 Vdc,	V _{EB(off)} = -0.5 Vdc)	I _{CEX}	-	-50	nAdc
$ Collector Cutoff Current \\ (V_{CB} = -50 \ Vdc, \ I_E = 0) \\ (V_{CB} = -50 \ Vdc, \ I_E = 0, \ T_A = 125^\circ C) $	I _{CBO}		-0.010 -10	μAdc	
Base Cutoff Current (V _{CE} = -30 Vdc, V _{EE}	_{3(off)} = -0.5 Vdc)	I _{BL}	-	-50	nAdc
ON CHARACTERISTICS					
$ \begin{array}{l} \text{DC Current Gain} \\ (I_{C} = -0.1 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -10 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -150 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \\ (I_{C} = -500 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}) \end{array} $	h _{FE}	75 100 100 100 50	- - - 300 -	_	
$\begin{array}{l} Collector-Emitter Saturation Voltage (Not $$ (I_C=-150 \mbox{ mAdc}, I_B=-15 \mbox{ mAdc})$ (Not $$ (I_C=-500 \mbox{ mAdc}, I_B=-50 \mbox{ mAdc})$ \end{array}$	V _{CE(sat)}		-0.4 -1.6	Vdc	
$\begin{array}{l} Base-Emitter \ Saturation \ Voltage \ (Note 4) \\ (I_C = -150 \ mAdc, \ I_B = -15 \ mAdc) \\ (I_C = -500 \ mAdc, \ I_B = -50 \ mAdc) \end{array}$	V _{BE(sat)}		-1.3 -2.6	Vdc	
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain - Bandwidth Product (Not (I _C = -50 mAdc, V _{CE} = -20 Vdc, f = 10	f _T	200	-	MHz	
Output Capacitance ($V_{CB} = -10$ Vdc, $I_E =$	= 0, f = 1.0 MHz)	C _{obo}	-	8.0	pF
Input Capacitance (V _{EB} = -2.0 Vdc, I _C =	C _{ibo}	-	30		
SWITCHING CHARACTERISTICS					
Turn-On Time		t _{on}	-	45	
Delay Time	(V _{CC} = -30 Vdc, I _C = -150 mAdc, I _{B1} = -15 mAdc)	t _d	-	10	
Rise Time	, ,	t _r	-	40	
Turn–Off Time		t _{off}	-	100	ns
Storage Time	torage Time $(V_{CC} = -6.0 \text{ Vdc}, I_C = -150 \text{ mAdc}, I_{B1} = I_{B2} = -15 \text{ mAdc})$		-	80	
Fall Time	<u> </u>	t _f	-	30	

4. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

5. f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.





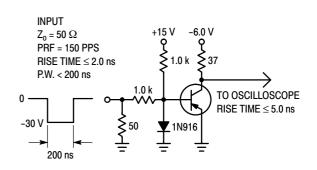
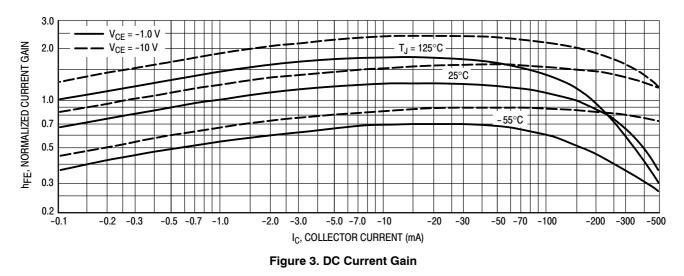
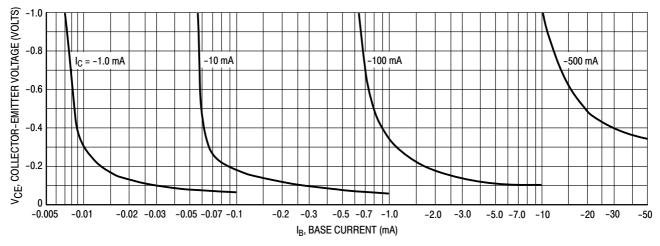
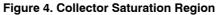


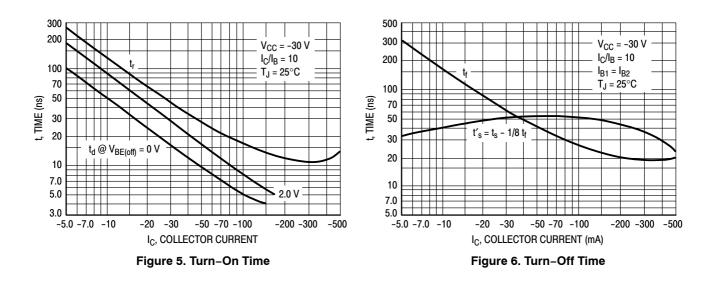
Figure 2. Storage and Fall Time Test Circuit

TYPICAL CHARACTERISTICS



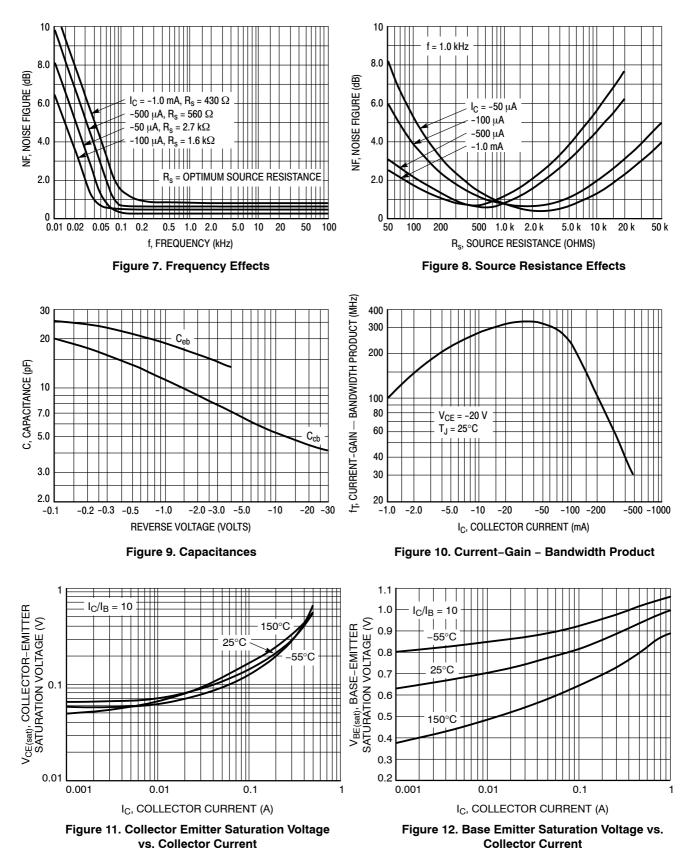






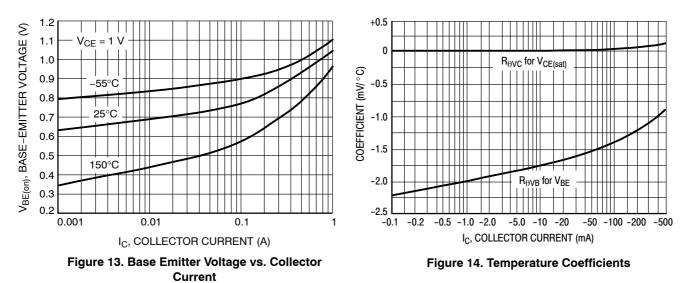
TYPICAL SMALL-SIGNAL Characteristics NOISE FIGURE

 V_{CE} = 10 Vdc, T_A = 25°C



TYPICAL SMALL-SIGNAL Characteristics NOISE FIGURE

 V_{CE} = 10 Vdc, T_A = 25°C



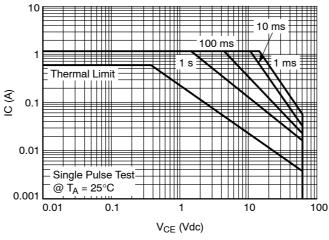
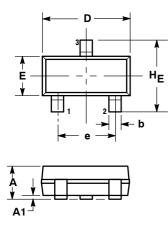
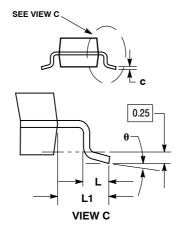


Figure 15. Safe Operating Area

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AN





NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF

BASE MATERIAL. 4. 318-01 THRU -07 AND -09 OBSOLETE,

4. 318-01 THRU -07 AND -09 OBS

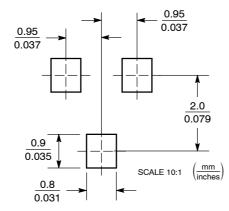
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6: PIN 1. BASE

1. BASE 2. EMITTER

3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and use registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typical" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death agosciated with such unintended or unauthorized use patent shall claims and so for the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for seale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative